

## Product Summary

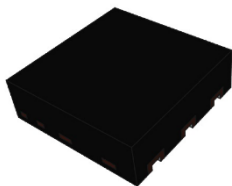
BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
-60V	155mΩ @ V <sub>GS</sub> = -10V	-2.5A
	240mΩ @ V <sub>GS</sub> = -4.5V	-2.0A

## Description and Applications

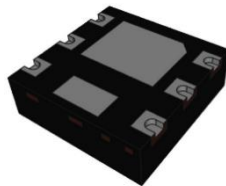
This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- Battery-management applications
- Power-management functions
- DC-DC converters

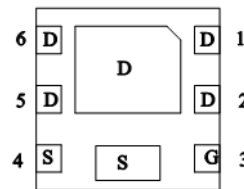
U-DFN2020-6/SWP (Type UXG)



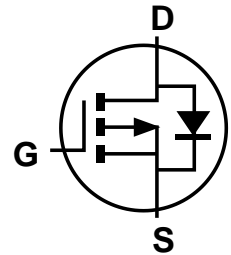
Top View



Bottom View



Pinout  
Bottom View



Equivalent Circuit

## Features and Benefits

- 100% Unclamped Inductive Switching (UIS) Test in Production — Ensures More Reliable and Robust End Application
- Low On-Resistance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. <https://www.diodes.com/quality/product-definitions/>

## Mechanical Data

- Package: U-DFN2020-6
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—NiPdAu over Copper Lead Frame, Solderable per MIL-STD-202, Method 208 Ⓔ4
- Weight: 0.007 grams (Approximate)

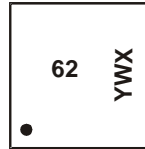
## Ordering Information (Note 4)

Orderable Part Number	Package	Packing	
		Qty.	Carrier
DMP6250SFDFW-7	U-DFN2020-6/SWP (Type UXG)	3,000	Reel
DMP6250SFDFW-13	U-DFN2020-6/SWP (Type UXG)	10,000	Reel

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  - See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  - For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information

U-DFN2020-6/SWP (Type UXG)



62 = Product Type Marking Code  
 YWX = Date Code Marking  
 Y = Year (ex: 5 = 2025)  
 W = Week (ex: a = week 27; z represents week 52 and 53)  
 X = Internal Code (ex: U = Monday)

Date Code Key

Year	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036
Code	5	6	7	8	9	0	1	2	3	4	5	6

Week	1-26	27-52	53
Code	A-Z	a-z	z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Y	Z

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	-60	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-2.5 -2.1	A
Continuous Source-Drain Diode Current (Note 5)		T <sub>A</sub> = +25°C	I <sub>S</sub>	-2.5	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-15	A
Avalanche Current, L = 0.1mH			I <sub>AS</sub>	-12	A
Avalanche Energy, L = 0.1mH			E <sub>AS</sub>	8	mJ

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	P <sub>D</sub>	1.2	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>θJA</sub>	103	°C/W
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	P <sub>D</sub>	1.8	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>θJA</sub>	69	°C/W
Thermal Resistance, Junction to Case	Steady State	R <sub>θJC</sub>	12	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.  
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-60	—	—	V	V <sub>GS</sub> = 0, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	-1	μA	V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1	—	-3	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	115	155	mΩ	V <sub>GS</sub> = -10V, I <sub>D</sub> = -2A
		—	148	240		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -1A
Diode Forward Voltage	V <sub>SD</sub>	—	-0.7	-1.2	V	V <sub>GS</sub> = 0, I <sub>S</sub> = -2A
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	C <sub>iss</sub>	—	612	—	pF	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0 f = 1MHz
Output Capacitance	C <sub>oss</sub>	—	36	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	26	—	pF	
Gate Resistance	R <sub>G</sub>	—	13	—	Ω	V <sub>DS</sub> = 0, V <sub>GS</sub> = 0, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = -10V)	Q <sub>g</sub>	—	8.9	—	nC	V <sub>DS</sub> = -30V, I <sub>D</sub> = -2A
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Q <sub>g</sub>	—	4.3	—	nC	
Gate-Source Charge	Q <sub>gs</sub>	—	1.4	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	1.7	—	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	—	7.6	—	ns	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -30V R <sub>G</sub> = 50Ω, I <sub>D</sub> = -1A
Turn-On Rise Time	t <sub>r</sub>	—	11.6	—	ns	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	—	79.8	—	ns	
Turn-Off Fall Time	t <sub>f</sub>	—	37.8	—	ns	
Reverse-Recovery Time	t <sub>RR</sub>	—	10.8	—	ns	I <sub>S</sub> = -1A, di/dt = 100A/μs
Reverse-Recovery Charge	Q <sub>rr</sub>	—	3.8	—	nC	I <sub>S</sub> = -1A, di/dt = 100A/μs

Notes: 7. Short duration pulse test used to minimize self-heating effect.  
8. Guaranteed by design. Not subject to product testing.

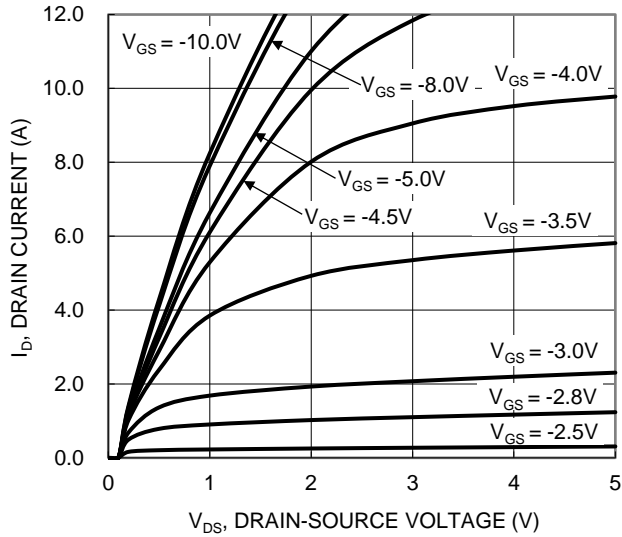


Figure 1. Typical Output Characteristic

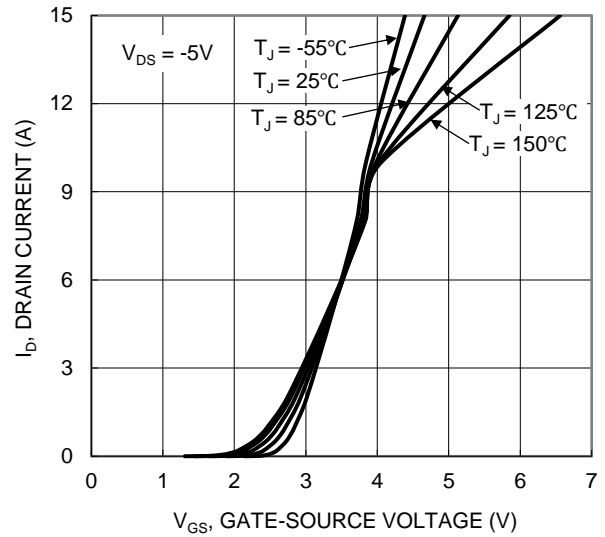


Figure 2. Typical Transfer Characteristic

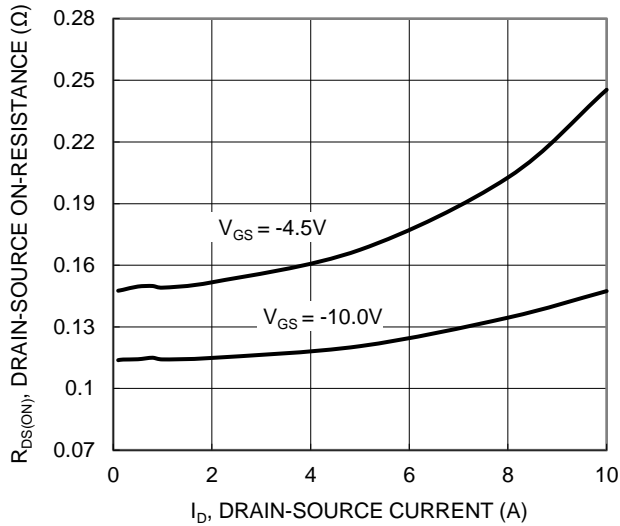


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

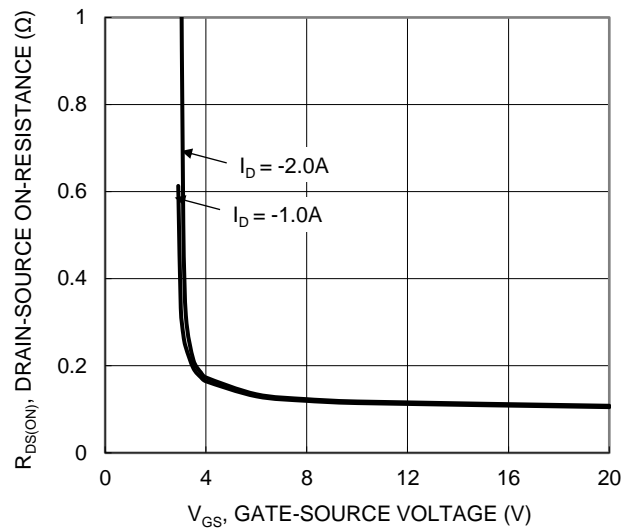


Figure 4. Typical Transfer Characteristic

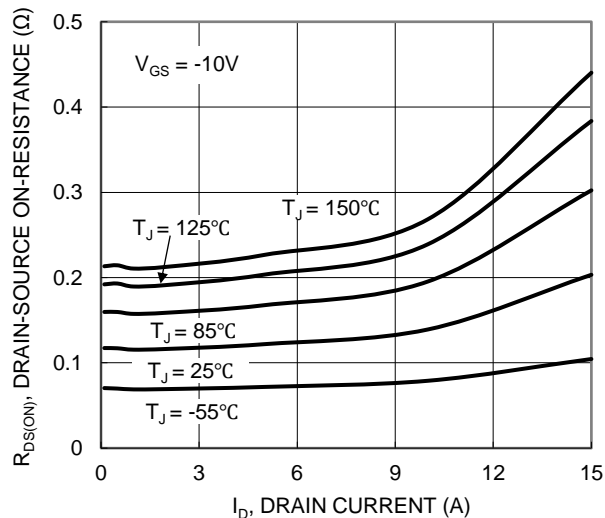


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

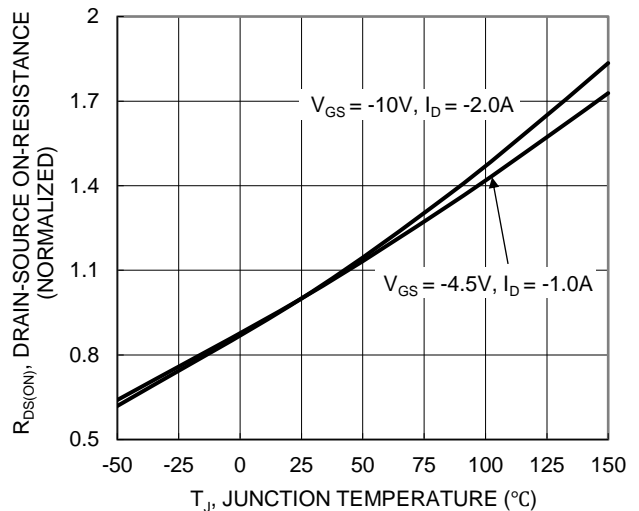


Figure 6. On-Resistance Variation with Junction Temperature

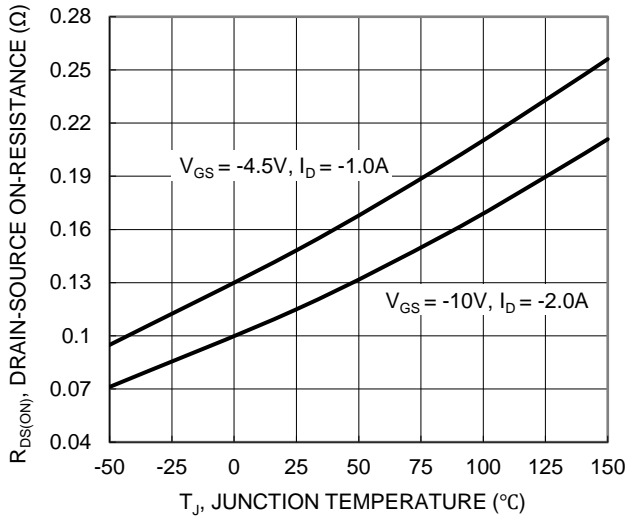


Figure 7. On-Resistance Variation with Junction Temperature

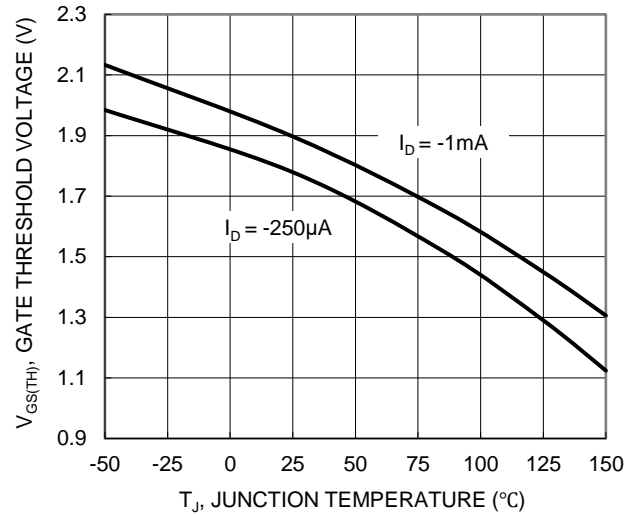


Figure 8. Gate Threshold Variation vs. Junction Temperature

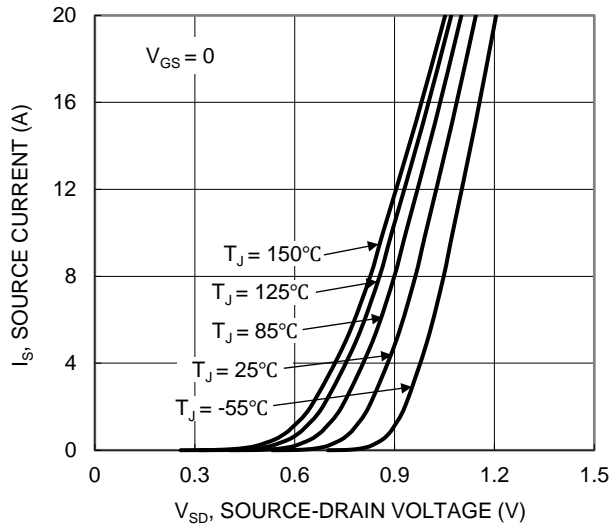


Figure 9. Diode Forward Voltage vs. Current

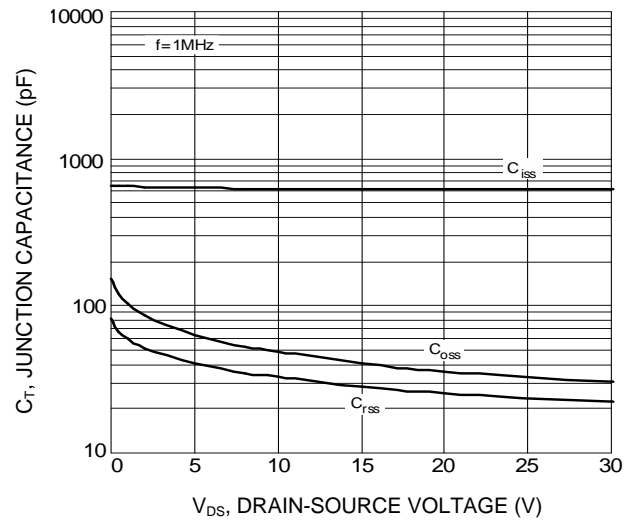


Figure 10. Typical Junction Capacitance

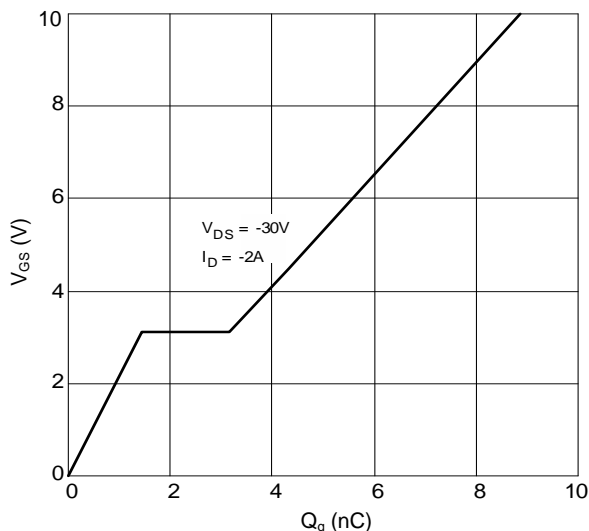


Figure 11. Gate Charge

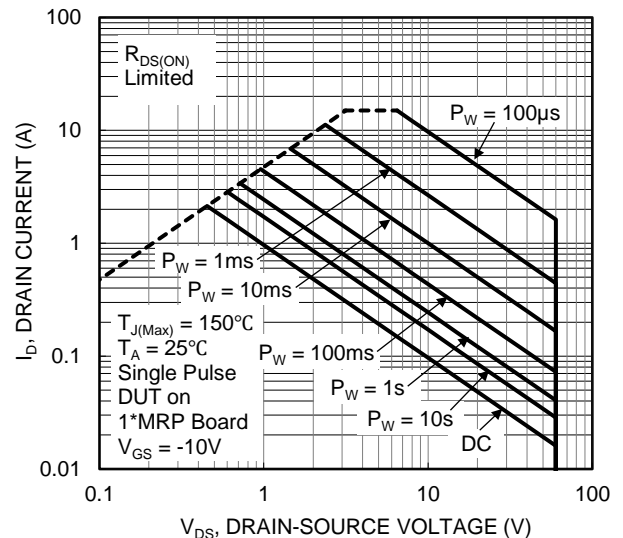


Figure 12. SOA, Safe Operation Area

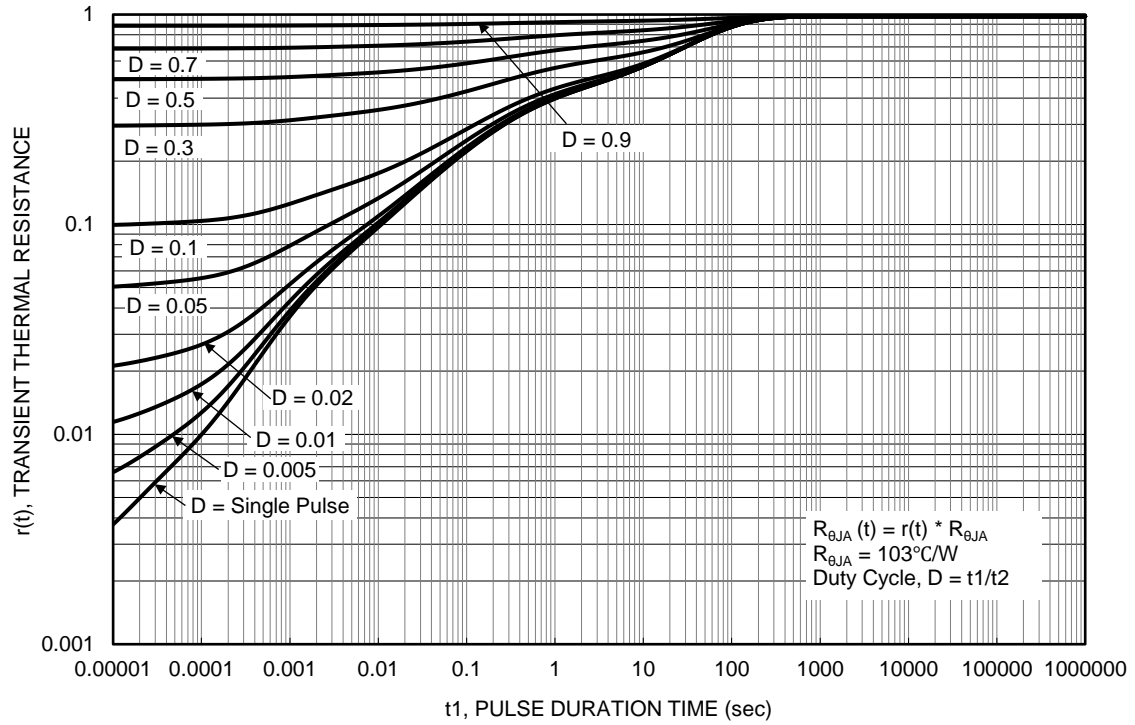
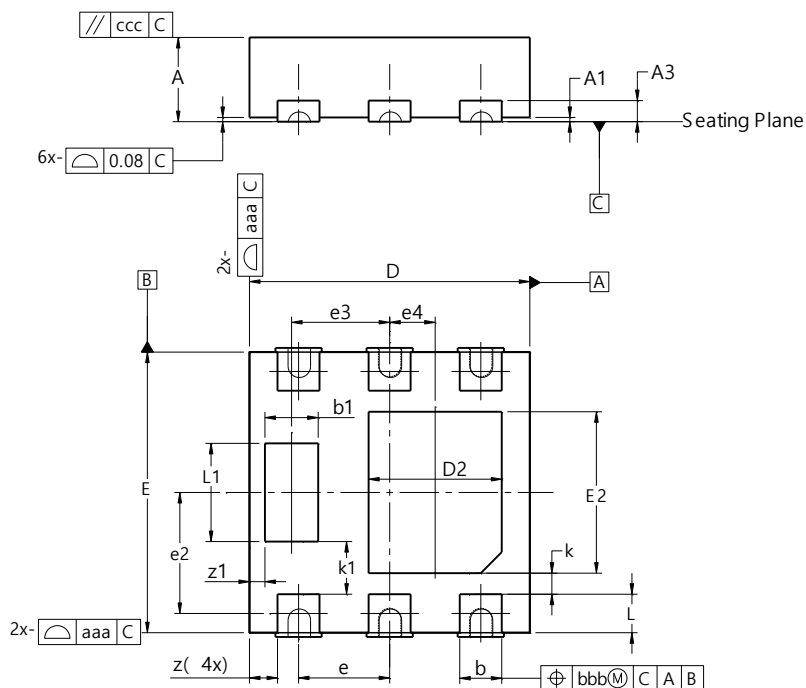


Figure 13. Transient Thermal Resistance

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### U-DFN2020-6/SWP (Type UXG)

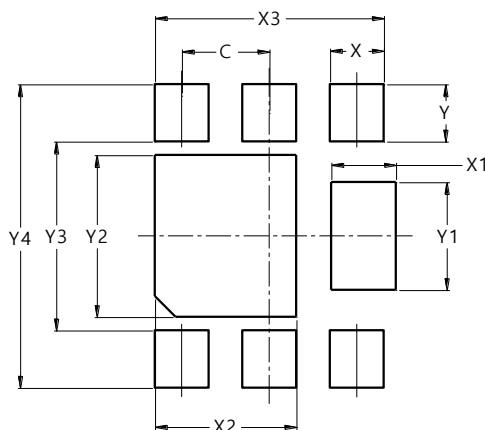


U-DFN2020-6/SWP (Type UXG)			
Dim	Min	Max	Typ
A	0.59	0.65	0.62
A1	0.00	0.05	0.03
A3	—	—	0.152
b	0.28	0.38	0.33
b1	0.35	0.45	0.40
D	1.95	2.05	2.00
D2	0.87	1.07	0.97
E	1.95	2.05	2.00
E2	1.07	1.27	1.17
e	0.65 BSC		
e3	0.70 BSC		
e4	0.325 BSC		
L	0.225	0.325	0.275
L1	0.67	0.77	0.72
k	—	—	0.15
k1	—	—	0.375
z	—	—	0.20
z1	—	—	0.11
aaa	0.25		
bbb	0.10		
ccc	0.10		
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### U-DFN2020-6/SWP (Type UXG)



Dimensions	Value (in mm)
C	0.650
X	0.350
X1	0.480
X2	1.050
X3	1.700
Y	0.425
Y1	0.800
Y2	1.200
Y3	1.400
Y4	2.250

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